

3.3-V Differential PECL/LVDS to TTL Translator

Check for Samples: [SN65EPT21](#)

FEATURES

- 1 ns Propagation Delay
- $F_{\max} > 300\text{MHz}$
- Operating Range: $V_{CC} = 3.0\text{ V to } 3.6\text{ V}$ with $GND = 0\text{ V}$
- 24-mA TTL Output
- Built-In Temperature Compensation
- Drop-In Compatible to the MC10EPT21, MC100EPT21

APPLICATIONS

- Data and Clock Transmission Over Backplane
- Signaling Level Conversion for Clock or Data

DESCRIPTION

The SN65EPT21 is a differential PECL-to-TTL translator. It operates on +3.3 V supply and ground only. The device includes circuitry to maintain inputs at $V_{CC}/2$ when left open.

The V_{BB} pin is a reference voltage output for the device. When the device is used in single-ended mode, the unused input should be tied to V_{BB} . This reference voltage can also be used to bias the input when it is ac coupled. When it is used, place a $0.01\mu\text{F}$ decoupling capacitor between V_{CC} and V_{BB} . Also limit the sink/source current to $< 0.5\text{ mA}$ to V_{BB} . Leave V_{BB} open when it is not used.

The SN65EPT21 is housed in an industry standard SOIC-8 package and is also available in an optional TSSOP-8 package.

PIN ASSIGNMENT(Add pullup on BOTH inputs)

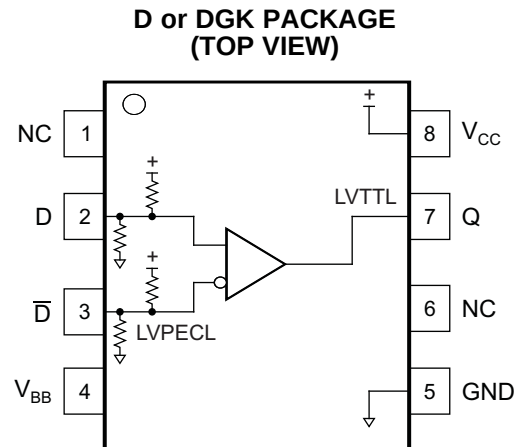


Table 1. Pin Descriptions

PIN	FUNCTION
Q	LVTTTL/LVCMOS Output
D, $\bar{D}$	Differential LVPECL/LVDS/CML Input
V_{CC}	Positive Supply
V_{BB}	Output Reference Voltage
GND	Ground
NC	No Connect
EP	(DFN8 only) Thermal exposed pad must be connected to a sufficient thermal conduit. Electrically connect to the most negative supply (GND) or leave unconnected, floating open.

ORDERING INFORMATION⁽¹⁾

PART NUMBER	PART MARKING	PACKAGE	LEAD FINISH
SN65EPT21D/DR	EPT21	SOIC	NiPdAu
SN65EPT21DGK/DGKR	SSSI	MSOP	NiPdAu

(1) Leaded device options are not initially available; contact a sales representative for further details.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

ABSOLUTE MAXIMUM RATINGS⁽¹⁾

PARAMETER	CONDITIONS	VALUE	UNIT
Absolute PECL mode supply voltage	V_{CC} (GND = 0 V)	3.8	V
Sink/source current, V_{BB}		± 0.5	mA
PECL input voltage	GND = 0 V, $V_I \leq V_{CC}$	0 to 3.8	V
Operating temperature range		–40 to 85	°C
Storage temperature range		–65 to 150	°C

- (1) Stresses beyond those listed under absolute maximum ratings may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any conditions beyond those indicated under recommended operating conditions is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

DISSIPATION RATINGS

PACKAGE	CIRCUIT BOARD MODEL	POWER RATING $T_A < 25^\circ\text{C}$ (mW)	THERMAL RESISTANCE, JUNCTION-TO-AMBIENT NO AIRFLOW	DERATING FACTOR $T_A > 25^\circ\text{C}$ (mW/°C)	POWER RATING $T_A = 85^\circ\text{C}$ (mW)
SOIC	Low-K	719	139	7	288
	High-K	840	119	8	336
MSOP	Low-K	469	213	5	188
	High-K	527	189	5	211

THERMAL CHARACTERISTICS

over operating free-air temperature range (unless otherwise noted)

PARAMETER			MIN	TYP	MAX	UNIT
θ_{JB}	Junction-to-board thermal resistance	SOIC		79		°C/W
		MSOP		120		
θ_{JC}	Junction-to-case thermal resistance	SOIC		98		°C/W
		MSOP		74		

KEY ATTRIBUTES

CHARACTERISTICS	VALUE
Internal input pull-down resistor	50 k Ω
Internal input pull-up resistor	50 k Ω
Moisture sensitivity level	Level 1
Flammability rating (oxygen index: 28 to 34)	UL 94 V-0 at 0.125 in
Electrostatic discharge	Human body model
	Charged-device model
	Machine mode
Meets or exceeds JEDEC Spec EIA/JESD78 latchup test	

PECL DC CHARACTERISTICS

At $V_{CC} = 3.3\text{ V}$, $GND = 0.0\text{ V}$ (unless otherwise noted)⁽¹⁾ ⁽²⁾

PARAMETER	TEST CONDITIONS	$T_A = -40^\circ\text{C}$			$T_A = 25^\circ\text{C}$			$T_A = 85^\circ\text{C}$			UNIT
		MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	
V_{IH}	High-level input voltage, single-ended	2075		2420	2075		2420	2075		2420	mV
V_{IL}	Low-level input voltage, single-ended	1355		1675	1355		1675	1355		1675	mV
V_{BB}	Output reference voltage	1910	2009	2160	1910	2034	2160	1910	2026	2160	mV
V_{IHCMR}	High-level input voltage, common-mode range, differential	1.2		3.3	1.2		3.3	1.2		3.3	V
I_{IH}	High-level input current			150			150			150	μA
I_{IL}	Low-level input current	-150			-150			-150			μA

- (1) The device will meet the specifications after thermal balance has been established when mounted in a socket or printed circuit board with maintained transverse airflow greater than 500 lfm. Electrical parameters are assured only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.
- (2) Input parameters vary 1:1 with V_{CC} .
- (3) $V_{IHCMR(\min)}$ varies 1:1 with GND , $V_{IHCMR(\max)}$ varies 1:1 with V_{CC} . V_{IHCMR} range is referenced to the most positive side of the differential input signal

TTL DC CHARACTERISTICS

At $V_{CC} = 3.3\text{ V}$, $GND = 0.0$, $T_A = -40^\circ\text{C}$ to 85°C (unless otherwise noted)⁽¹⁾

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
I _{CCH}	Power supply current	Output is HIGH	5	9	20	mA
I _{CCL}	Power supply current	Output is LOW	8	7.5	26	mA
V _{OH}	High-level output voltage	I _{OH} = −3.0 mA	2.4	3.05		V
V _{OL}	Low-level output voltage	I _{OL} = 24 mA		0.32	0.5	V
I _{OS}	Output short circuit current		−180	−100	−80	mA

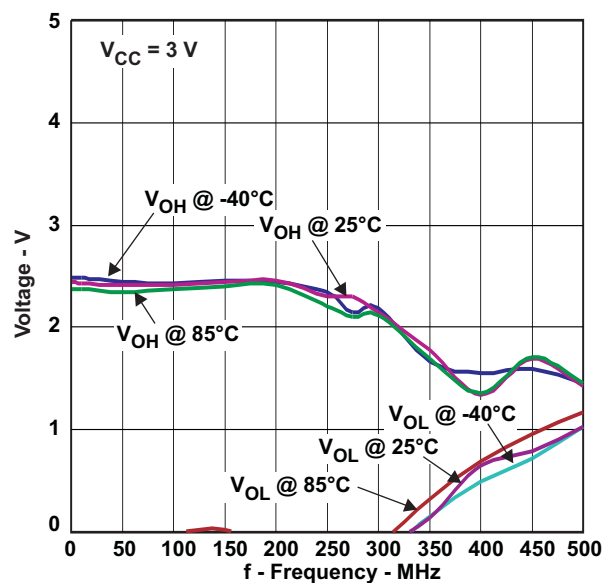
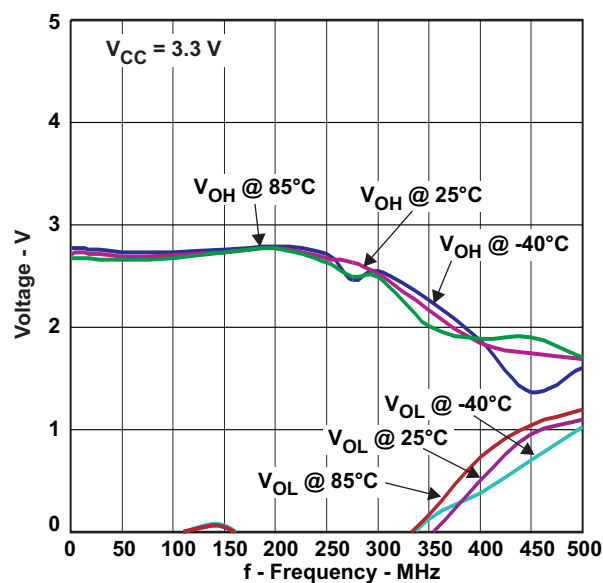
- (1) The device will meet the specifications after thermal balance has been established when mounted in a socket or printed circuit board with maintained transverse airflow greater than 500 lfm. Electrical parameters are assured only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

AC CHARACTERISTICS

At $V_{CC} = 3.0\text{ V}$ to 3.6 V , $GND = 0.0\text{ V}$ (unless otherwise noted)⁽¹⁾ ⁽²⁾

PARAMETER		TEST CONDITIONS	T _A = −40°C			T _A = 25°C			T _A = 85°C			UNIT
			MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	
f _{MAX}	Maximum switching frequency (Figure 1–Figure 3)		300			300			300			MHz
t _{PLH}	Propagation delay	At 1.5 V	1000	1394	1800	1000	1444	1800	1000	1481	1800	ps
t _{PHL}	Propagation delay	At 1.5 V	1000	1140	1900	1000	1280	1900	1000	1421	1900	ps
t _{JITTER}	Random clock jitter (RMS)		2.25		5	3.2		5	3.4		5	ps
t _{SKEW}	Duty Cycle Skew ⁽³⁾		94		250	78		250	62		250	ps
t _{SKPP}	Part-to-Part Skew ⁽³⁾		500			500			500			ps
V _{PP}	Input swing	See ⁽⁴⁾	150		1200	150		1200	150		1200	mV
t _r /t _f	Output rise/fall times	Q, $\overline{Q}$ (0.8V - 2.0V))	250	500	900	250	500	900	250	500	900	ps

- (1) The device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfm. Electrical parameters are assured only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.
- (2) $R_L = 500\ \Omega$ to GND and $C_L = 20\text{ pF}$ to GND . See Figure 4. Measured with 750mV, 50% duty cycle clock source
- (3) Skews are measured between outputs under identical transitions
- (4) $V_{PP(\min)}$ is minimum input swing for which ac parameters are assured.

Figure 1. Maximum Switching Frequency $V_{CC} = 3.0\text{ V}$ Figure 2. Maximum Switching Frequency $V_{CC} = 3.3\text{ V}$

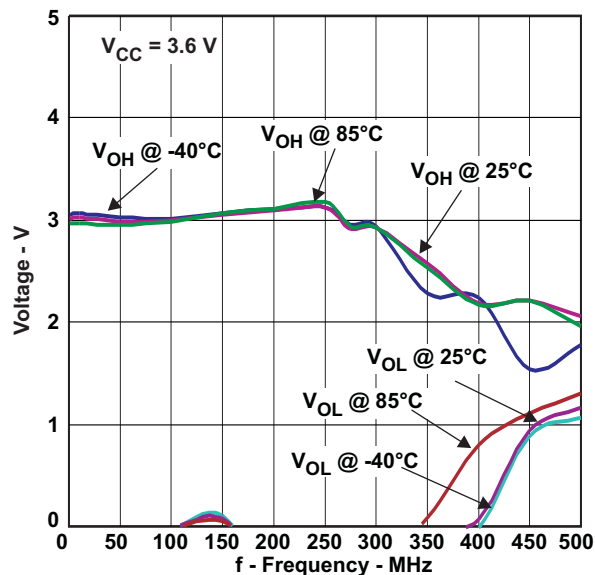


Figure 3. Maximum Switching Frequency $V_{CC}= 3.6\text{ V}$

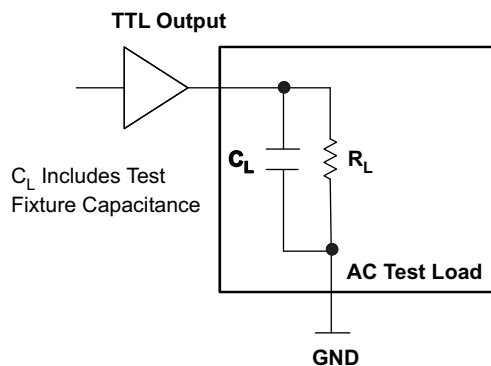


Figure 4. TTL Output AC Test Loading Condition

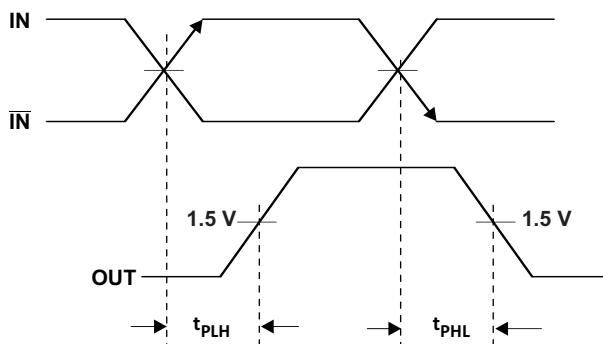
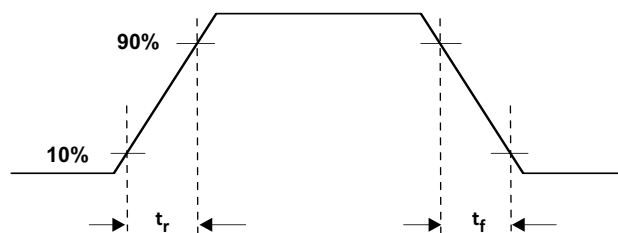


Figure 5. Output Propagation Delay

**Figure 6. Output Rise and Fall Times**

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
SN65EPT21D	Active	Production	SOIC (D) 8	75 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	EPT21
SN65EPT21D.B	Active	Production	SOIC (D) 8	75 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	EPT21
SN65EPT21DGK	Active	Production	VSSOP (DGK) 8	80 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	SSSI
SN65EPT21DGK.B	Active	Production	VSSOP (DGK) 8	80 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	SSSI
SN65EPT21DGKG4	Active	Production	VSSOP (DGK) 8	80 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	SSSI
SN65EPT21DGKG4.B	Active	Production	VSSOP (DGK) 8	80 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	SSSI
SN65EPT21DGKR	Active	Production	VSSOP (DGK) 8	2500 LARGE T&R	Yes	Call TI Nipdau	Level-1-260C-UNLIM	-40 to 85	SSSI
SN65EPT21DGKR.B	Active	Production	VSSOP (DGK) 8	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	SSSI
SN65EPT21DR	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	EPT21
SN65EPT21DR.B	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	EPT21

⁽¹⁾ **Status:** For more details on status, see our [product life cycle](#).

⁽²⁾ **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

⁽⁴⁾ **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

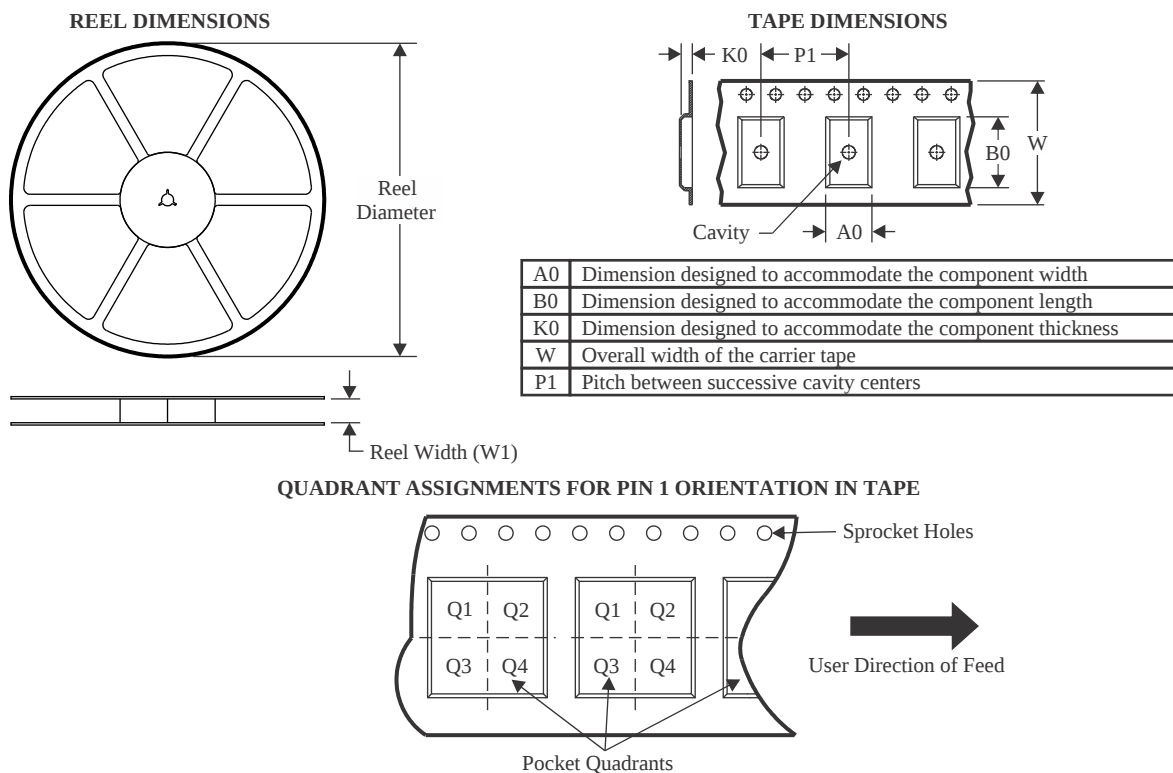
Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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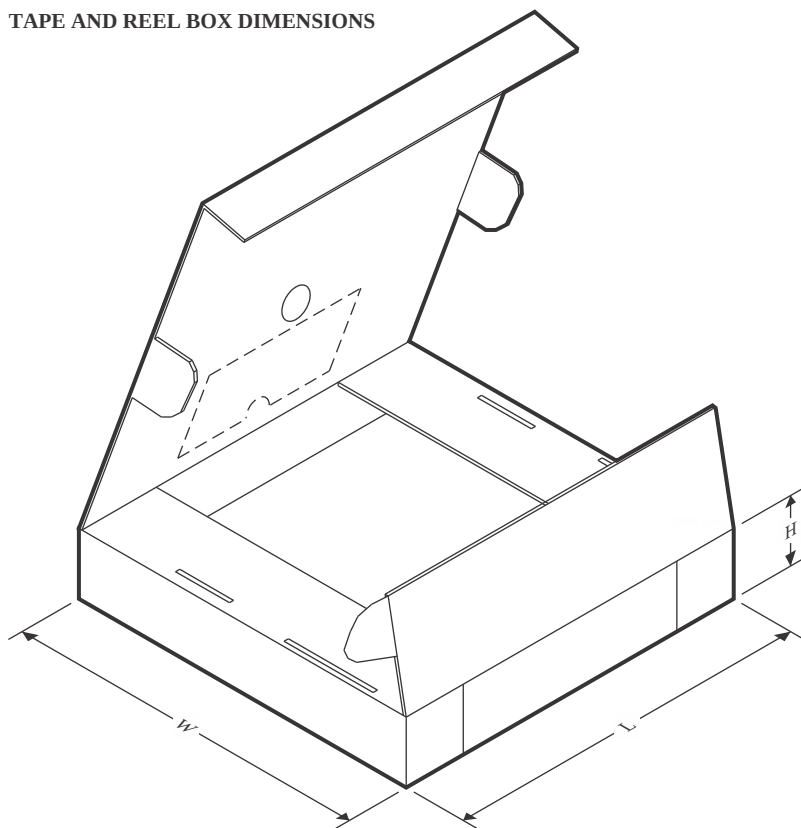
TAPE AND REEL INFORMATION



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN65EPT21DR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

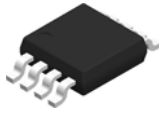
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN65EPT21DR	SOIC	D	8	2500	356.0	356.0	35.0

TUBE


*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
SN65EPT21D	D	SOIC	8	75	506.6	8	3940	4.32
SN65EPT21D.B	D	SOIC	8	75	506.6	8	3940	4.32
SN65EPT21DGK	DGK	VSSOP	8	80	330.2	6.6	3005	1.88
SN65EPT21DGK.B	DGK	VSSOP	8	80	330.2	6.6	3005	1.88
SN65EPT21DGKG4	DGK	VSSOP	8	80	330.2	6.6	3005	1.88
SN65EPT21DGKG4.B	DGK	VSSOP	8	80	330.2	6.6	3005	1.88

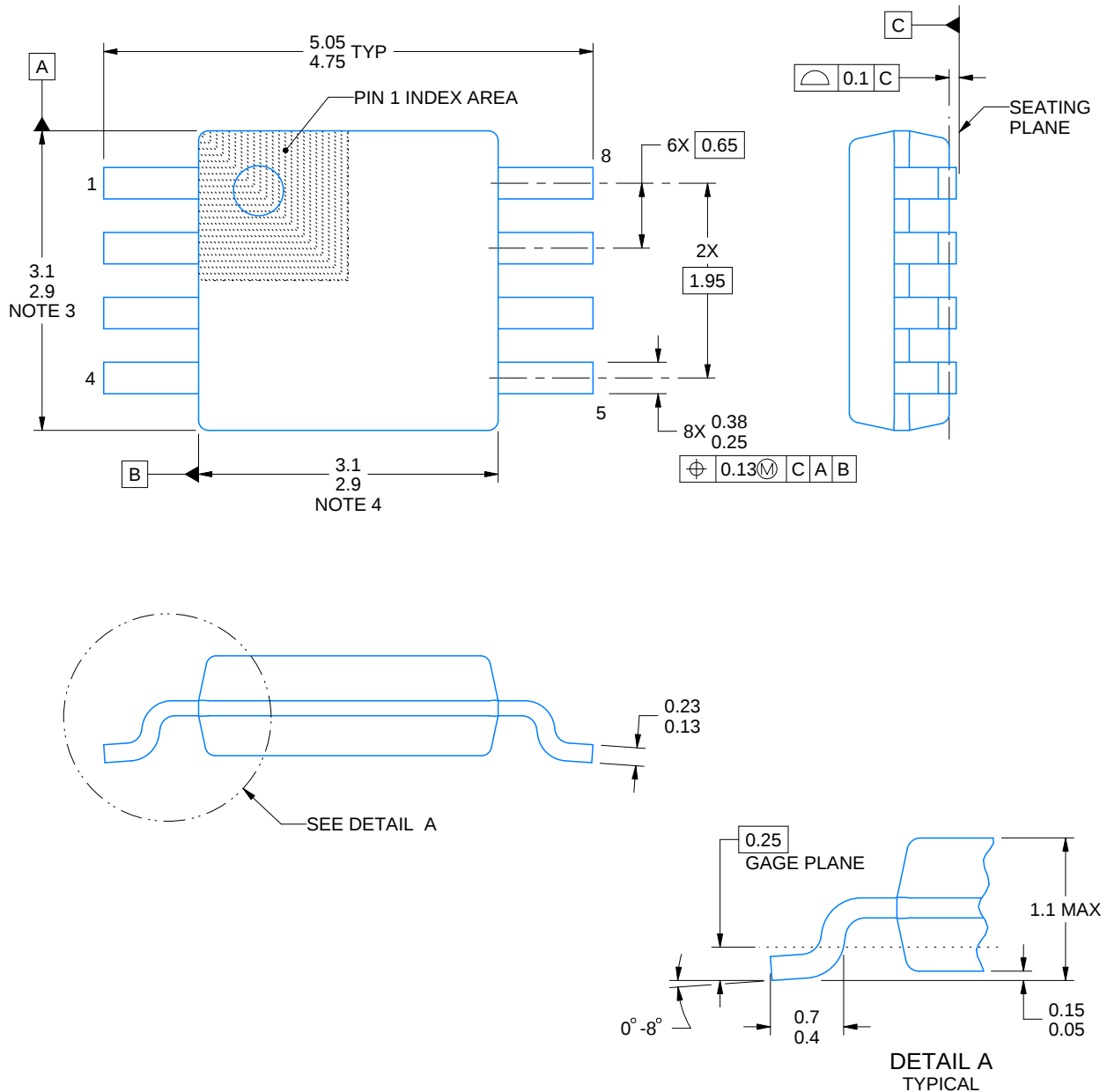
DGK0008A



PACKAGE OUTLINE

VSSOP - 1.1 mm max height

SMALL OUTLINE PACKAGE



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NOTES:

PowerPAD is a trademark of Texas Instruments.

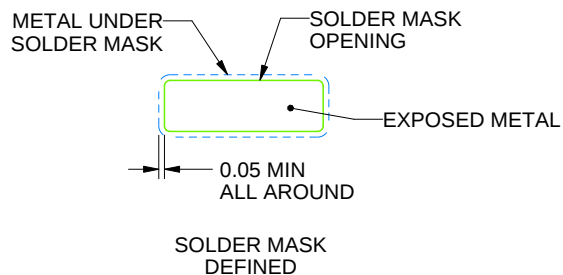
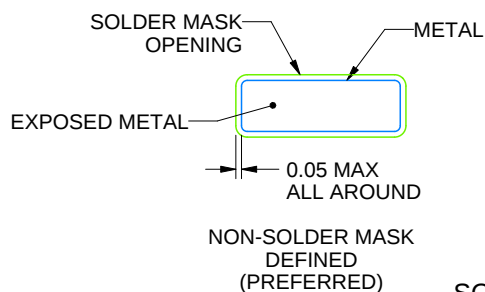
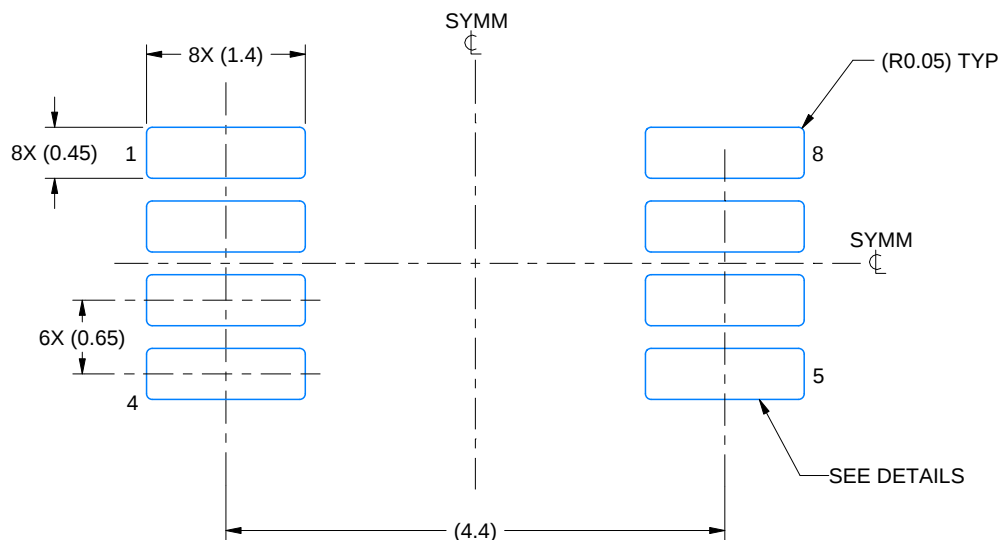
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-187.

EXAMPLE BOARD LAYOUT

DGK0008A

TM VSSOP - 1.1 mm max height

SMALL OUTLINE PACKAGE



SOLDER MASK DETAILS

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NOTES: (continued)

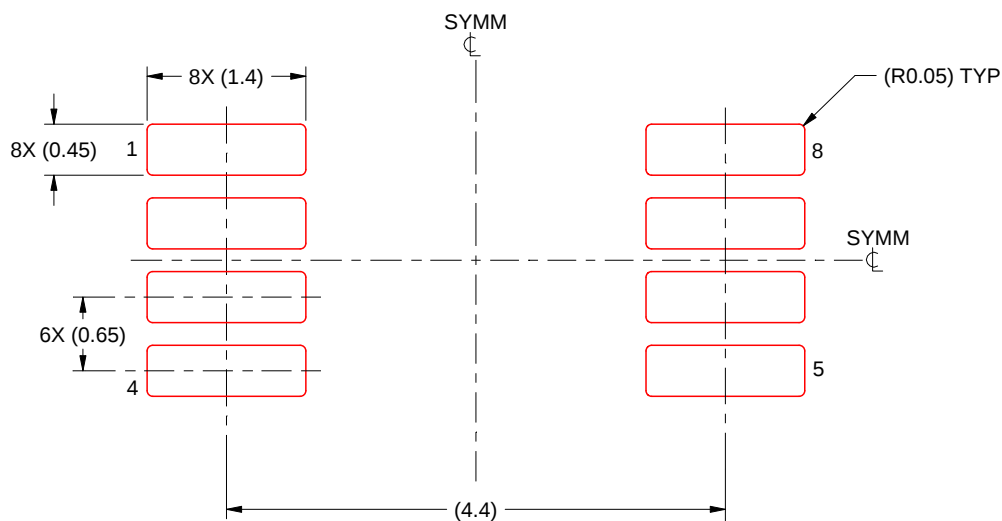
6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.
8. Vias are optional depending on application, refer to device data sheet. If any vias are implemented, refer to their locations shown on this view. It is recommended that vias under paste be filled, plugged or tented.
9. Size of metal pad may vary due to creepage requirement.

EXAMPLE STENCIL DESIGN

DGK0008A

TM VSSOP - 1.1 mm max height

SMALL OUTLINE PACKAGE

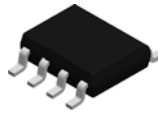


SOLDER PASTE EXAMPLE
SCALE: 15X

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NOTES: (continued)

11. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
12. Board assembly site may have different recommendations for stencil design.

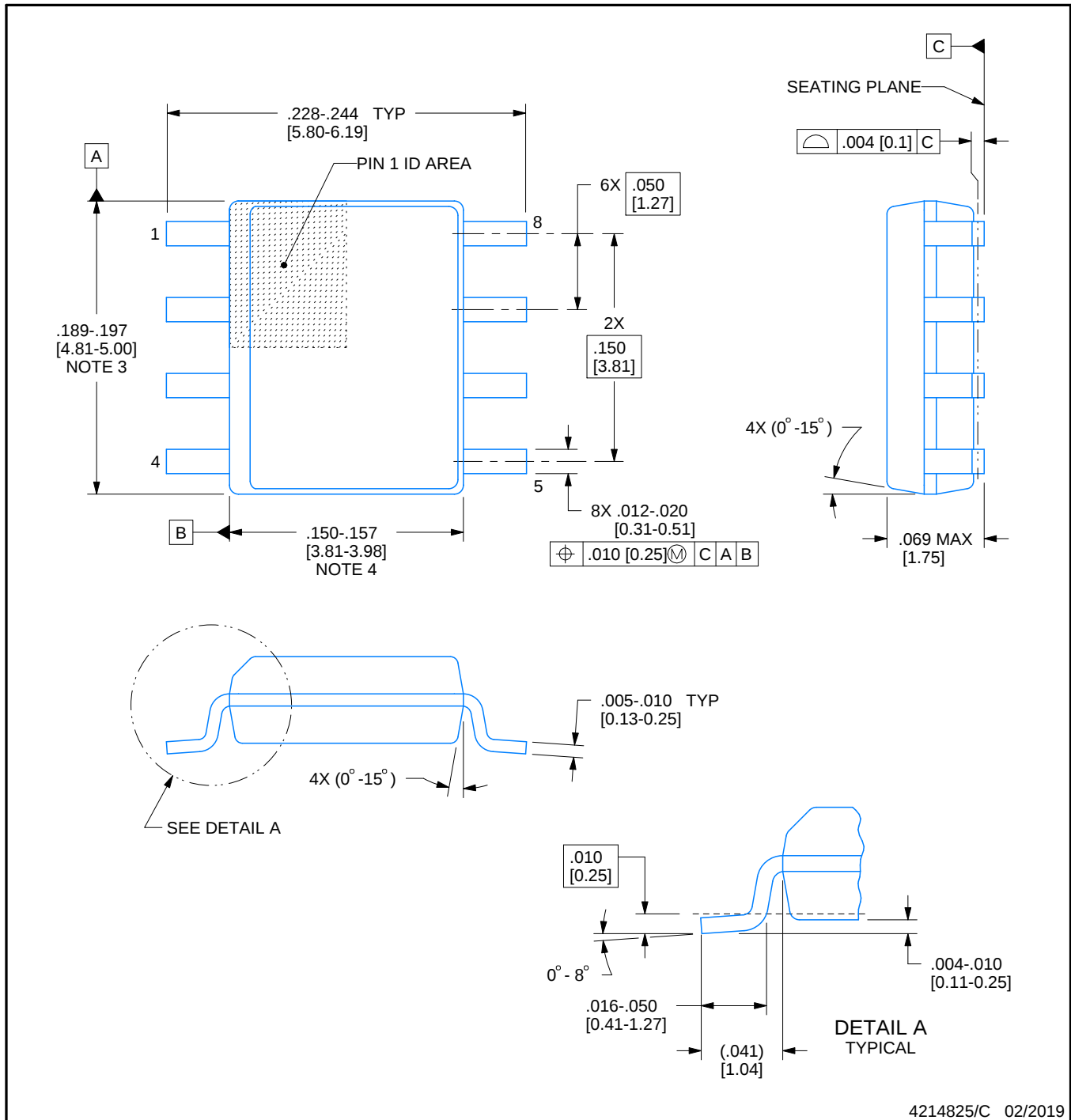


D0008A

PACKAGE OUTLINE

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



4214825/C 02/2019

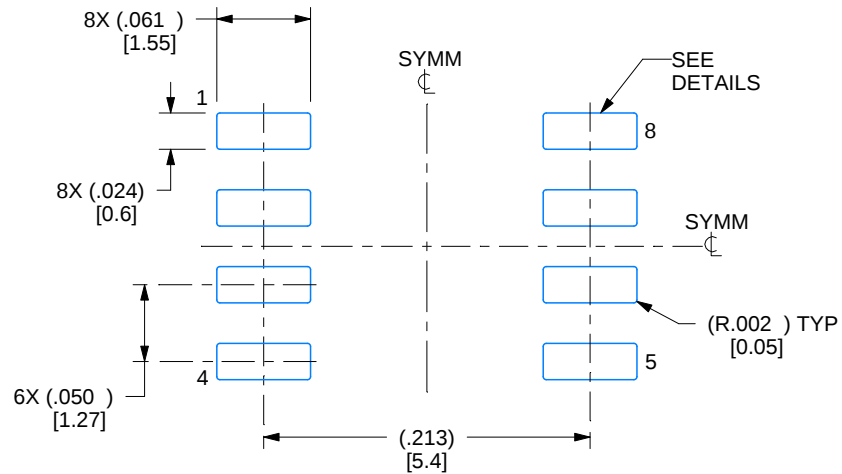
NOTES:

1. Linear dimensions are in inches [millimeters]. Dimensions in parenthesis are for reference only. Controlling dimensions are in inches. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 [0.15] per side.
4. This dimension does not include interlead flash.
5. Reference JEDEC registration MS-012, variation AA.

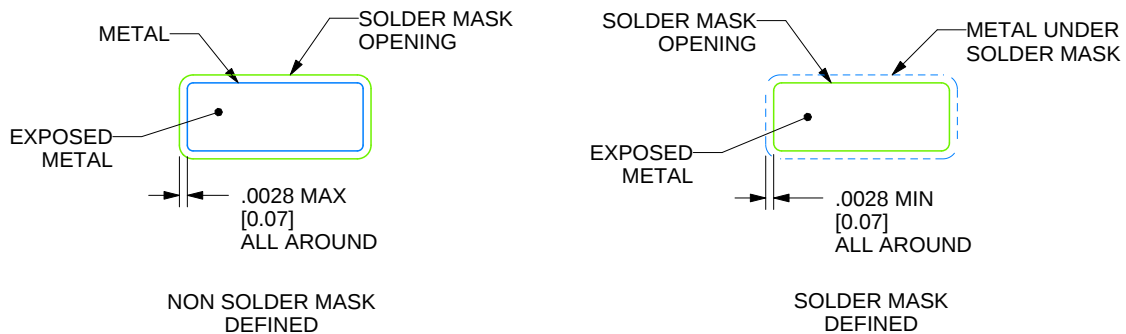
D0008A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE:8X



SOLDER MASK DETAILS

4214825/C 02/2019

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

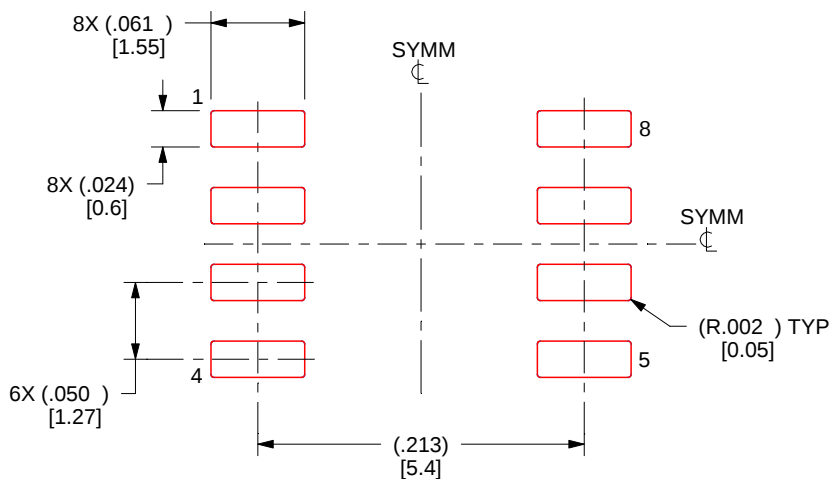
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

D0008A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



SOLDER PASTE EXAMPLE
BASED ON .005 INCH [0.125 MM] THICK STENCIL
SCALE:8X

4214825/C 02/2019

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

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